Semicon Europa: booth B1-1519

ERS electronic will showcase manufacturing innovation at Semicon Europa

Munich, 2nd November, 2017 – ERS electronic GmbH, the innovation leader in the market of thermal test solutions for semiconductor manufacturing, will be showcasing their innovative technology at Semicon Europa. Together with Productronica, the world's leading manufacturing trade fair held in parallel, the event is the largest microelectronics meeting place in Europe. For ERS' numerous European customers, this represents an excellent opportunity to receive an update on the company's innovation in terms of products and technology.

ERS has a solid and growing installed base among Europe's highly advanced semiconductor manufacturers and research institutions. While today more than 50 per cent of ERS shipments are made to customers in Asia, Europe and its semiconductor industry remain essential for innovation and product development. ERS runs a support centre in Europe's semiconductor manufacturing stronghold, Dresden. In addition, the company has established an eWLB (advanced Wafer Level Packaging) competence centre in Munich to address the fast growing FOWLP (Fan Out Wafer Level Packaging) markets in the semiconductor value chain backend. Through these activities, ERS maintains a close working relationship with its customers, including multiple key players in semiconductor testing. "The trust that our customers place in us gives us great momentum in the market. Our presence at the Semicon Europa will give us the opportunity to engage with our customer, share first-hand information about our new products and developments and give them a chance to discuss their needs with us", says Laurent Giai-Miniet, CSMO of ERS electronic GmbH.

Yole Développement (Yole) confirms the impressive penetration of FOWLP in the advanced packaging industry: "Driven by numerous added values, including good electrical performance, high integration capability and small form factor for limited cost, the market doubled between 2015 and 2017 with Apple choosing TSMC's FOWLP for their application processor", explains Jérôme Azémar, Activity Developer, Advanced Packaging & Semiconductor Manufacturing at Yole. "This trend will keep going with a 20% CAGR1 from 2017 to 2022, thanks to other major players adopting FOWLP, explains the strategy consulting & market research company 2."

At Semicon Europa, ERS will once again be demonstrating its innovation strength. "We will be releasing a complete new family of chucks, developed in cooperation with an industry leader", explains Laurent Giai-Miniet. "This is the 4th generation of innovation in thermal chucks".
"In the long run, we expect that our FOWLP activity will be as big as our thermal chuck business" Giai-Miniet adds.

Cost efficiency and accuracy in testing

All sub-markets and applications of semiconductor technology are characterized by rapid technological progress. Each new generation of chips features smaller geometries, higher operating frequencies and lower energy consumption. This progress can only be achieved if the semiconductors are subjected to ever more rigorous tests during the course of their production. These tests in turn enable an increased level of accuracy, repeatability, flexibility and cost-effectiveness for the test procedures. The test equipment from ERS electronic meets these requirements thanks to the outstanding expertise of its developers and their proverbial quality awareness. ERS' development and production of AirCool systems takes place exclusively in Germany.

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[1] CAGR : Compound Annual Growth Rate
[2] Source : Fan-Out: Technologies and Market trends report, Yole Développement, 2017

The level of quality, together with the advanced design of ERS products, has allowed ERS to gain market share. In 2016 and 2017 alone, revenue generated from thermal chucks increased 33 per cent.

About ERS:
ERS electronic GmbH, based in Germering near Munich, has been producing innovative thermal test solutions for the semiconductor industry for 47 years. The company has gained an outstanding reputation in the sector, notably with its fast and accurate thermal chuck systems for test temperatures ranging from -65°C to +550°C for analytical, parameter-related and manufacturing tests. Today, thermal chuck systems developed by ERS in its product families AC3, AirCool©, AirCool© plus and PowerSense© are an integral component in all larger-sized wafer probers right across the semiconductor industry.

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